



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



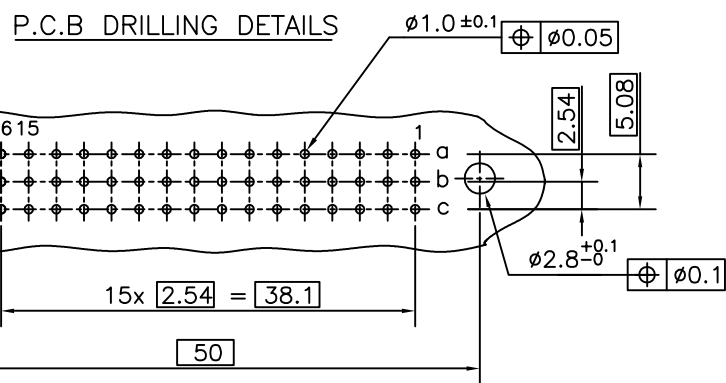
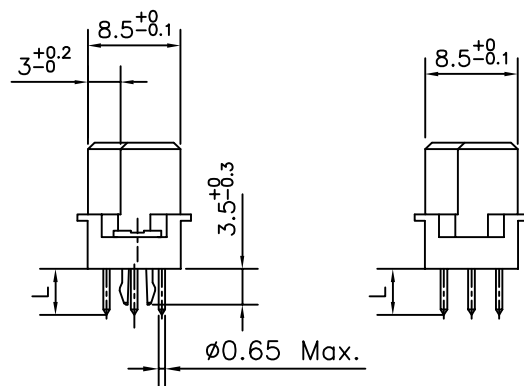
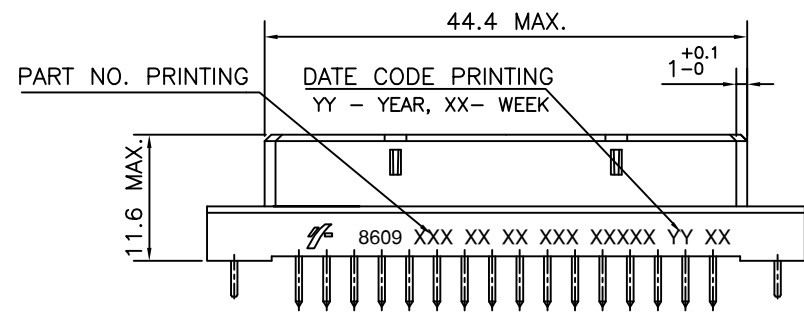
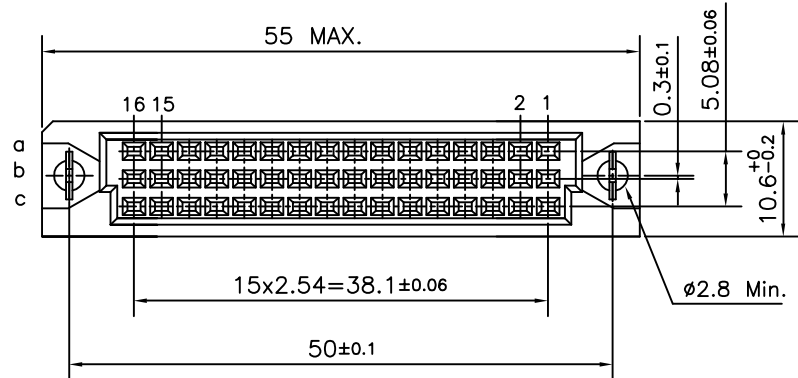
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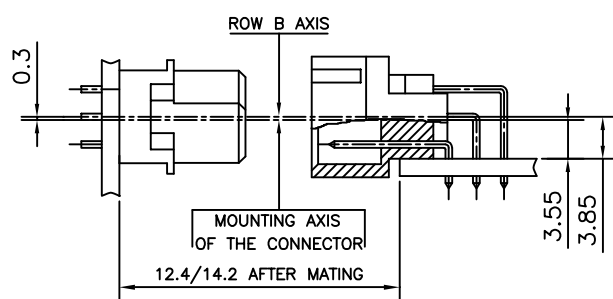
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

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24	2.5
14	4.0
TERM. STYLE	L ^{+0.7} ₋₀



TECHNICAL SPECIFICATION

HOUSING MATERIAL : THERMOPLASTIC POLYESTER UL94V-0, GREY
 HOUSING CAN WITHSTAND EXPOSURE TO LEAD FREE WAVE SOLDERING TEMPERATURE OF 260-265°C FOR STRAIGHT CONNECTORS AS IT IS IN CLASSICAL LEAD WAVE SOLDERING AT 235-250°C

CONTACT / HARPOON MATERIAL : COPPER ALLOY
 CONTACT PLATING : GOLD OVER NICKEL
 ACTIVE ZONE : GOLD OVER NICKEL
 TERMINATION ZONE : GOLD OVER NICKEL
 TIN LEAD VERSION : TIN LEAD OVER NICKEL
 LEAD FREE VERSION : TIN (PURE MATTE) OVER NI
 HARPOON PLATING : TIN LEAD OVER NICKEL
 TIN LEAD VERSION : TIN LEAD OVER NICKEL
 LEAD FREE VERSION : TIN (PURE MATTE) OVER NI

ELECTRICAL DATA
 CURRENT RATING AT 20°C : 1.5 A
 CURRENT (I MAX) : 2 A
 TEMPERATURE RANGE : -55°C/+125°C
 CONTACT RESISTANCE : ≤ 20mΩ
 INSULATION RESISTANCE : ≥ 10⁶ MΩ
 TEST VOLTAGE (rms) : 1000V

MECHANICAL DATA
 INSERTION FORCE PER CONTACT : ≤ 0.94N
 EXTRACTION FORCE PER CONTACT : ≥ 0.15N

REFERENCE SPECIFICATIONS : DIN 41612 / IEC 603-2

SERIES	8609	3	48	8	3	14	7	5	5	000E1
ROWS FITTED WITH CONTACTS										
Rows a b c		3	48							
Rows a - c		4	32							
NUMBER OF CONTACTS										
TYPE OF INSULATOR										
3 ROW FEMALE INSULATOR										8
METHOD OF MOUNTING										
STANDARD MOUNTING - STYLE C/2										3
TERMINATION										
LONG STRAIGHT SPILL (L - SEE TABLE)										14
SHORT STRAIGHT SPILL (L - SEE TABLE)										24
OPTIONS										
NO OPTION										7
WITH HARPOONS										H
PERFORMANCE CLASS										
DIN 41612 CLASS 3										4
DIN 41612 CLASS 2										5
DIN 41612 CLASS 1										6
AS PER MIL C 55302/ JSS 50808										8
PITCH PER ROW										
2.54										5
000E1										TIN LEAD VERSION
E1LF										LEAD FREE VERSION

mat'l. code		surface		tolerance		projection		product family	
-		ISO 1302		ISO 406 ISO 1101				8609	
ltr		ecn no		dr		date		title	
A		I04-0100		MINI		09/11/2004		DIN STANDARD RECEPTACLE	
B		I05-0042		MINI		19/05/2005		STRAIGHT SPILL DIN 41612 STYLE-C/2	
C		I06-0062		MINI		01/06/2006			
				dr		MINI K VANDANATH 22/09/2004		dwg no	
				engr		RAKHEE GEORGE 22/09/2004		sheet 1 of 1	
				chr		RAKHEE GEORGE 01/06/2006		size	
				appd		RAKHEE GEORGE 01/06/2006		A3	
sheet index		revision		C				type	
		sheet		1				Product Customer Drawing	

NOTES:-
 1. THE "LF" PRODUCTS MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
 2. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 3.5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6 MM MINIMUM THICK CIRCUIT BOARD
 3. LEAD FREE OR RoHS DIRECTIVE LABELING TO BE PROVIDED AS PER GS-14-920 FOR LEAD FREE VERSION.



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